

Customer No.: 31561
Application No.: 10/709,990
Docket No.: 11416-US-PA

AMENDMENTS

IN THE CLAIMS:

Please amend the claims according to the following listing of claims and substitute it for all prior versions and listing of claims in the application.

1. (currently amended) A solder composition, comprising:
chromium (Cr) in an amount of 5~20 wt.%;
stibium (Sb) in an amount of 0.01~50 wt.%;
a component selected from a-the group consisting of tin (Sn), zinc (Zn), bismuth (Bi), indium (In) and a mixture thereof; and
an impurity.
2. (currently amended) The solder composition according to claim 1, further comprising another component selected from a-the IVB group in the periodic table or a mixture thereof in an amount of 0.01~10 wt. %.
3. (currently amended) The solder composition according to claim 1, further comprising another component selected from a-the VB group in the periodic table or a mixture thereof in an amount of 0.01~10 wt. %.

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4. (currently amended) The solder composition according to claim 1, further comprising another component selected from ~~a~~the IIIB group in the periodic table or a mixture thereof in an amount of 0.01~20 wt.%.

5. (original) The solder composition according to claim 4, wherein the component selected from the IIIB group in the periodic table or a mixture thereof at least comprises cerium (Ce), samarium (Sm), neodymium (Nd), lutetium (Lu) or a mixture thereof.

6. (original) The solder composition according to claim 1, further comprising another component selected from silver (Ag), copper (Cu) or a mixture thereof having an amount of 0.01~10 wt.%.

7. (cancelled).

8. (original) The solder composition according to claim 1, further comprising another component selected from nickel (Ni), cobalt (Co), manganese (Mn) or a mixture thereof in an amount of 0.01~5 wt.%.

9. (original) The solder composition according to claim 1, further comprising gallium (Ga) in an amount of 0.01~10 wt.%.

10. (currently amended) A solder composition, comprising:

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chromium (Cr) in an amount of 0.01~5 wt.%;

stibium (Sb) in an amount of 0.01~50 wt.%;

a component selected from ~~a~~the group consisting of tin (Sn), zinc (Zn), bismuth (Bi), indium (In) and a mixture thereof; and
an impurity.

11. (original) The solder composition according to claim 10, further comprising another component selected from silver (Ag), copper (Cu) or a mixture thereof having an amount of 0.01~10 wt.%.

12. (cancelled).

13. (original) The solder composition according to claim 10, further comprising another component selected from nickel (Ni), cobalt (Co), manganese (Mn) or a mixture thereof in an amount of 0.01~5 wt.%.

14. (original) The solder composition according to claim 10, further comprising gallium (Ga) in an amount of 0.01~10 wt.%.